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U.S. DEPARTMENT OF COMMERCE
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10/13/00
689838

No : 50212-142

PATENTS ONLY

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of Conveying Parties:

Yoichi SUZUKI and Naoki OKA

2. Name and address of receiving party:

Name: Applied Materials Inc.

Address: 3050 Bowers Avenue

Santa Clara, California 95054

Additional name(s) of conveying party(ies) attached? ☐ Yes

3. Nature of Conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: October 7, 2000

Additional name(s) & address(es) attached? ☐ Yes

4. Application number(s) or patent number(s): 09/689838

If the document is being filed together with a new application, the execution date of the application is: October 7, 2000

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached? ☐ Yes

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: MCDERMOTT, WILL & EMERY

Internal Address:

Street Address: 600 13th Street, N.W.

City: Washington State: DC Zip: 20005

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)

\$40.00

☐ Enclosed☒ Authorized to be charged to deposit account

8. Deposit account number:

500417

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document

Stephen A. Becker, 26,527

October 13, 2000

Name and Registration No. of Person Signing

Signature

Date

Total number of pages comprising cover sheet: 1

CMB No. 0851-0011 (exp. 4/94)

10/18/2000 SSANDARA 00000013 500417 09689838

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PATENT
REEL: 011283 FRAME: 0629

ASSIGNMENT

Whereas, I/we,

NameAddress1) **Yoichi SUZUKI**

c/o Applied Materials Japan Inc.,

14-3, Shinizumi,
Narita-shi, Chiba 286-8516 Japan2) **Naoki OKA**c/o Applied Materials Japan Inc.,
14-3, Shinizumi,
Narita-shi, Chiba 286-8516 Japan

hereinafter called assignor(s), have invented certain improvements in

METHOD OF MANUFACTURING SEMICONDUCTOR INTEGRATED CIRCUIT

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

Whereas filed on _____, Serial No. _____; and

APPLIED MATERIALS INC.3050 Bowers Avenue,
Santa Clara, California 95054 United States of America

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

INVENTORSDATE SIGNED

1):

Name:

*Yoichi Suzuki***Yoichi SUZUKI***10/17/00*

2):

Name:

*Naoki Oka***Naoki OKA***October 7, 2000*

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. § 261)